产品规格承认书

SPECIFICATIONS

	各尸:								
	CUSTOME	ER: _							
	产品名和	沵:							
			:			Internal A	Intenna		
	客户型点	号:							
	CUSTOME	R PA	RT No:			CSA			
	产品型學	号:							
	OUR MOD	EL N	0:		3	216MA01			
	日期:								
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3216MA01 Specification

Operating Temp. : -40 ℃~+85 ℃

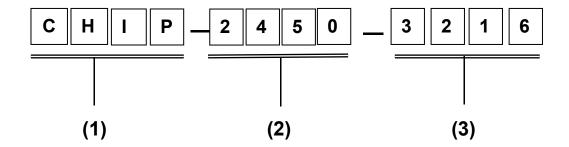
1. FEATURES:

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

2. APPLICATIONS:

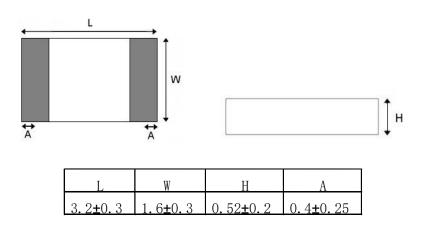
- Bluetooth, Wireless LAN, Mobile TV
- Home RF system, etc

3. PRODUCT IDENTIFICATION

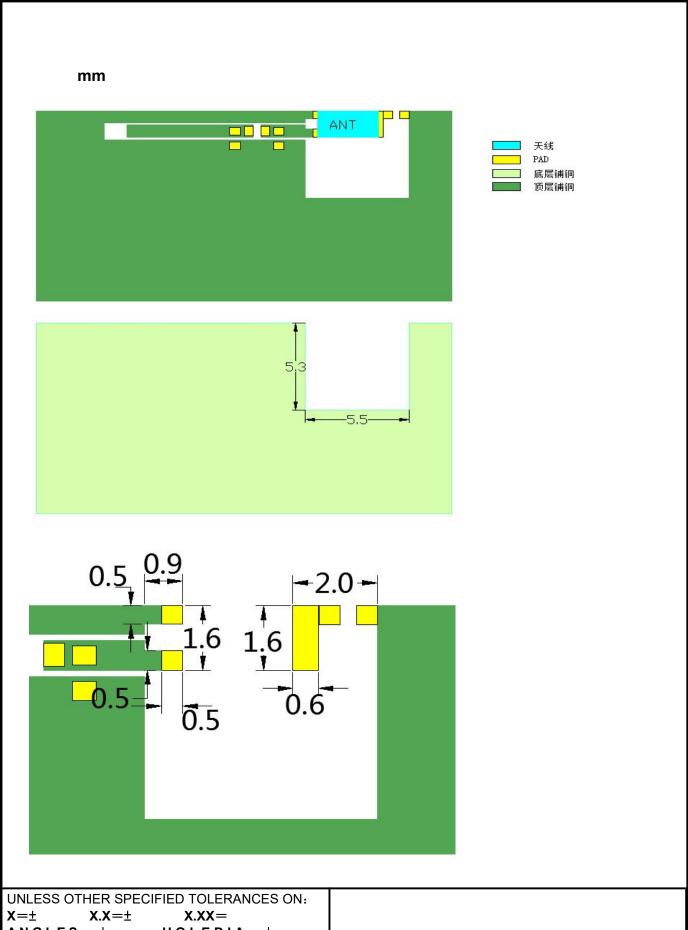


- (1) Product type: Multilayer chip Antenna
- (2) Center Frequency: 2450MHz
- (3) External Dimensions (L×W) (mm): 3.2*1.6

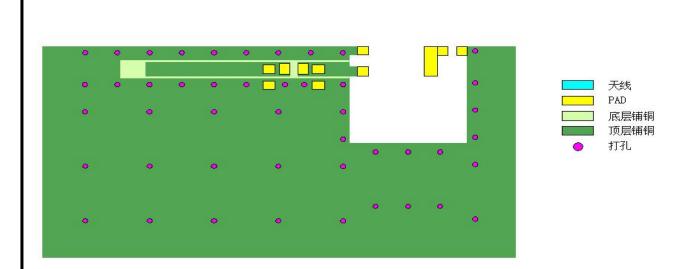
4. SHAPE AND DIMENSIONS:



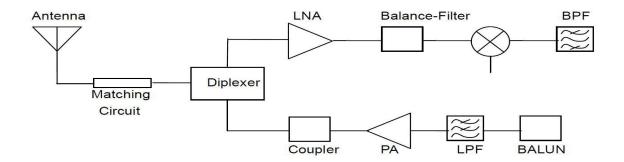
UNLESS OTHER SPECIFIED TOLERANCES ON:				
$X=\pm$ $X.X=\pm$	X.XX =			
$ANGLES = \pm$	$HOLEDIA = \pm$			
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		aihua cave Industrial Park, (
DESIGNED BY: Sera APPROVED BY: XD		New Distr	ict, Shenzhen, China	
TITLE: CHIP2450-21 Specification		DOCUMENT 3216		SPEC REV.
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TITLE: CHIF2430-21 Specification		NO.	3210	P1
TITLE: CHIP2450-21 Specification		DOCUMENT	3216	SPEC REV.
DESIGNED BY: Sera	APPROVED BY: XD	New Distr	ict, Shenzhen, China	
DRAWN BY : Sera	CHECKED BY: XD	B 3 floor, Ba	aihua cave Industrial Park, G	uangming
SCALE: N/A	UNIT: mm	Shenzhe	en Famulia Technology Co.,l	Ltd
$ANGLES = \pm$	$HOLEDIA = \pm$			
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UNLESS OTHER SPEC	FIED TOLERANCES ON:			



APPLICATION GUIDE



5. SPECIFICATIONS:

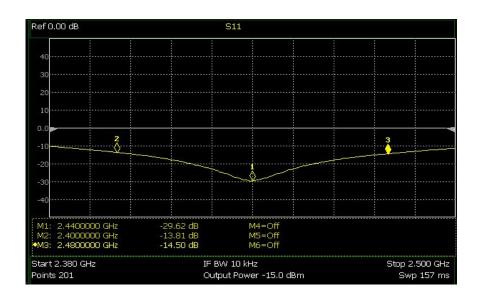
Frequency←	2.4 – 2.5 GHz←	4
Impedance←	50ohm nominal ²	4
V.S. <u>W.R</u> ←	≤1.92←	4
Return loss←	≤-10dB←	4
Radiation←	Omni-directional←	4
Gain (Peak)←	2G: 2.67dBi←	4

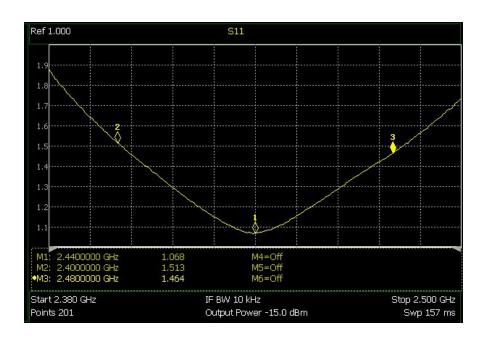
* Test condition: Test board size 90*40 mm

Matching circuit: Pi matching circuit will be required

UNLESS OTHER SPECIFIED TOLERANCES ON:				
$X=\pm$ $X.X=\pm$	x.xx =			
$ANGLES = \pm$	$HOLEDIA = \pm$			
SCALE: N/A	UNIT: mm	Shenzhe	en Famulia Technology Co.,l	Ltd
DRAWN BY : Sera	CHECKED BY: XD	B 3 floor, Baihua cave Industrial Park, Guangming		uangming
DESIGNED BY: Sera				
TITLE: CHIP2450-21 Specification		DOCUMENT	3216	SPEC REV.
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6. Electrical Characteristics:



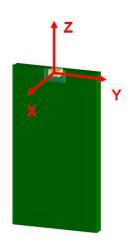


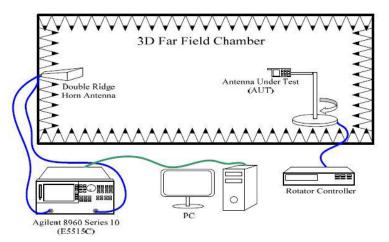
Mark	Frequency	VSWR
1	2400 MHz	1.513
2	2440 MHz	1.068
3	2480 MHz	1.464

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$ANGLES = \pm$	$HOLEDIA = \pm$			
SCALE: N/A	UNIT: mm	Shenzhe	en Famulia Technology Co.,L	.td
DRAWN BY : Sera	CHECKED BY: XD	B 3 floor, Baihua cave Industrial Park, Guangmin		
DESIGNED BY: Sera	APPROVED BY: XD	New District, Shenzhen, China		
TITLE: CHIP2450-21 Specification		DOCUMENT	3216	SPEC REV.
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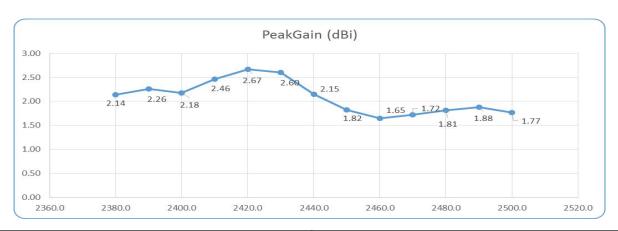
Radiation Pattern

The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator,a standard horn antenna and Vector Network Analyzer is used to collect data.



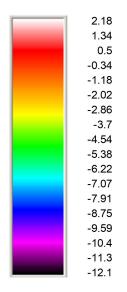


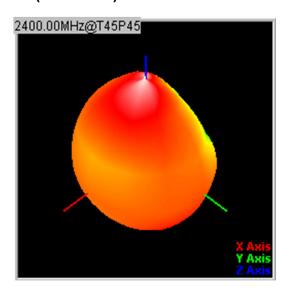


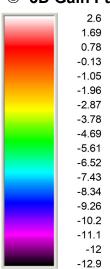


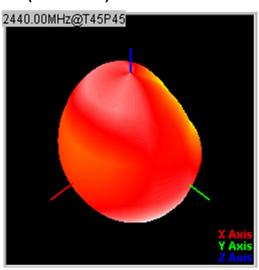
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DRAWN BY : Sera CHECKED BY: XD		B 3 floor, Baihua cave Industrial Park, Guangmin			
DESIGNED BY:	DESIGNED BY: Sera APPROVED BY: XD New District, Shenzhen, China				
TITLE: CHIP2450-21 Specification		DOCUMENT	3216	SPEC REV.	
TITLE: CHIP2450-21 Specification			NO.	3210	D1

○ 3D Gain Pattern (2400 MHz)

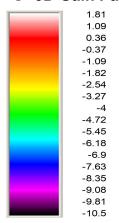


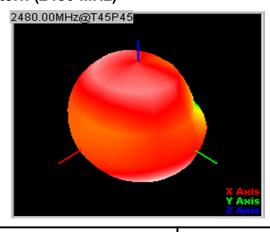






O 3D Gain Pattern (2480 MHz)





DESIGNED BY: Sera TITLE: CHIP2450-21 Sp	APPROVED BY: XD	DOCUMENT	ct, Shenzhen, China 3216	SPEC REV.
DRAWN BY : Sera	CHECKED BY: XD	B 3 floor, Baihua cave Industrial Park, Guangming		
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$ANGLES = \pm$	$HOLEDIA = \pm$			
$X=\pm$ $X.X=\pm$	x.xx =			
UNLESS OTHER SPEC	IFIED TOLERANCES ON:			

7. Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	 30±3 minutes at -40° C±5° C, Convert to +105° C (5 minutes) 30±3 minutes at +105° C±5° C, Convert to -40° C (5 minutes) Total 100 continuous cycles 	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: $85\pm5^{\circ}$ C 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: 150° C $\pm 5^{\circ}$ C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: -40° C $\pm 5^{\circ}$ C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : $260\pm5^{\circ}\!$	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of $245\pm5^\circ\!$	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within $0 \sim 30^{\circ}$ C and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

(b) On board:

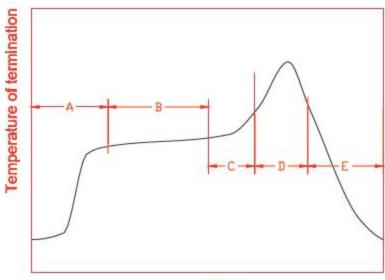
The temperature should be within -40~85°C and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40 $^{\circ}$ C to +105 $^{\circ}$ C.

UNLESS OTHER SPECI	FIED TOLERANCES ON:			
$X=\pm$ $X.X=\pm$	X.XX =			
$ANGLES = \pm$	$HOLEDIA = \pm$			
SCALE: N/A	UNIT: mm	Shenzhe	en Famulia Technology Co.,L	td
DRAWN BY : Sera	CHECKED BY: XD	B 3 floor, Baihua cave Industrial Park, Guangming		
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TITLE: CHIP2450-21 Specification		DOCUMENT	3216	SPEC REV.
11122: 31111 2430-21 3p		NO.	3210	P1

8. Recommended Reflow Soldering



Time

Α	1 st rising temperature	The normal to Preheating temperature	30s to 60s
В	Preheating	140°C to 160°C	60s to 120s
С	2 nd rising temperature	Preheating to 200°C	20s to 40s
		if 220°C	50s∼60s
D Main heating		if 230°C	40s~50s
	Main heating	if 240°C	30s~40s
	5-00-00-00-00-00-00-00-00-00-00-00-00-00	if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s

^{*}reference: J-STD-020C

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

- (a) The tip temperature must be less than 350° C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

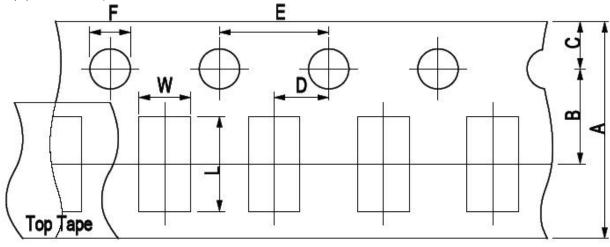
Note that excess of soldering volume will easily get crack the body of this product.

UNLESS OTHER SPECIFIED TOLERANCES ON:				
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SCALE: N/A	UNIT: mm	Shenzhen Famulia Technology Co.,Ltd		
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DESIGNED BY: Sera	APPROVED BY: XD	New District, Shenzhen, China		
TITLE: CHIP2450-21 S	necification	DOCUMENT	3216	SPEC REV.
111122: 31111 2430-21 3	pecinication	NO. 3210		P1

9. Taping Package and Label Marking: (unit: mm)

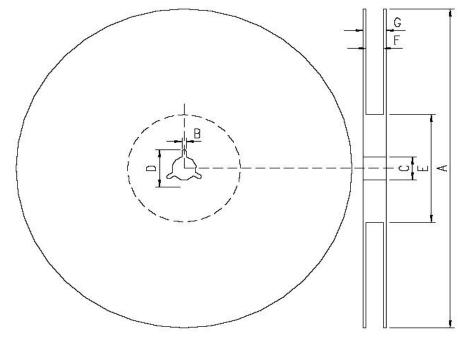
(1) Quantity/Reel: 5000pcs/Reel

(2) Carrier tape dimensions



Type	A	В	С	D	Е	F	L	W
2450-21	8.00 ± 0.3	3.50 ± 0.05	1.75±0.1	2.00 ± 0.05	4.00 ± 0.1	1.50 ± 0.1	2.30 ± 0.1	1.55 \pm 0.1

(3) Taping reel dimensions



Α	178.0±2.0
В	2.0±0.5
C	13.0±0.5
D	21.0±0.8
Ε	62.0±1.5
F	9.0±0.5
G	13.0±1.0

UNLESS OTHER SPECIFIED TOLERANCES ON:				
$X=\pm$ $X.X=\pm$	x.xx =			
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SCALE: N/A	UNIT: mm	Shenzhen Famulia Technology Co.,Ltd		
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